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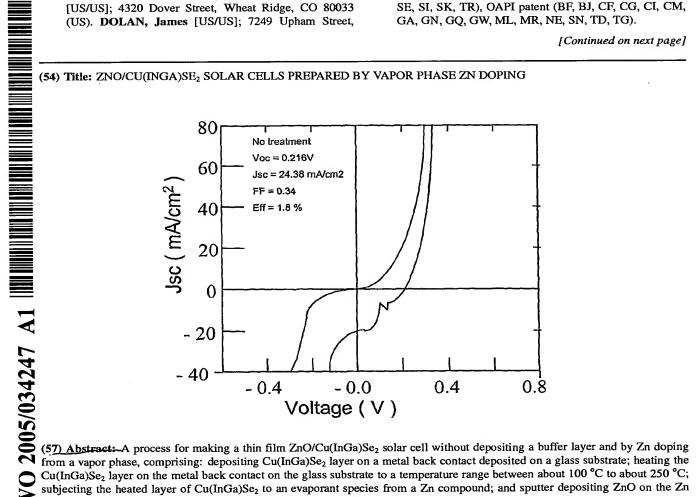
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Cu(InGa)Se2 layer on the metal back contact on the glass substrate to a temperature range between about 100 °C to about 250 °C; subjecting the heated layer of Cu(InGa)Se2 to an evaporant species from a Zn compound; and sputter depositing ZnO on the Zn compound evaporant species treated layer of Cu(InGa)Se2.